

Rail-to-rail input/output 20MHz GBP operational amplifiers

Features

- Low input offset voltage: 1.5mV max
- Rail-to-rail input and output
- Wide bandwidth 20MHz, stable for gain ≥ 3
- Low power consumption: 1.1mA maximum
- High output current: 35mA
- Operating from 2.5V to 5.5V
- Low input bias current, 1pA typ
- ESD internal protection $\geq 5kV$
- Latch-up immunity

Description

The TSV991/2/4 family of single, dual & quad operational amplifiers offers low voltage operation and rail-to-rail input and output.

This family features an excellent speed/power consumption ratio, offering a 20MHz gain-bandwidth, stable for gain above 3 (100pF capacitive load), while consuming only 1.1mA max at 5V supply voltage. It also features an ultra-low input bias current.

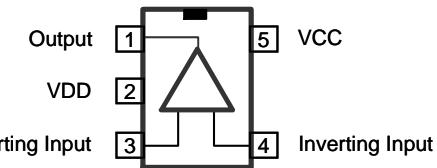
These characteristics make the TSV991/2/4 family ideal for sensor interfaces, battery-supplied and portable applications, as well as active filtering.

Applications

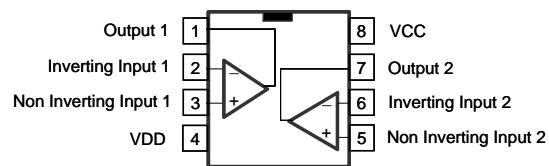
- Battery-powered applications
- Portable devices
- Signal conditioning
- Active filtering
- Medical instrumentation

Pin connections (top view)

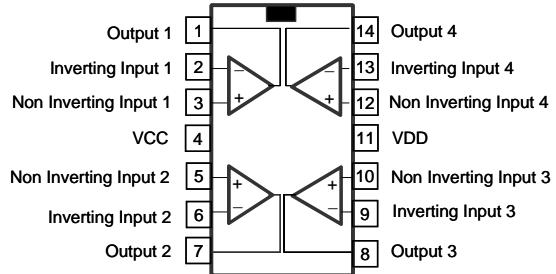
SOT23-5



MSO-8, SO-8



SO-14, TSSOP14



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1 Absolute maximum ratings & operating conditions

Table 1. Absolute maximum ratings (AMR)

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage ⁽¹⁾	6	V
V_{id}	Differential input voltage ⁽²⁾	$\pm V_{CC}$	V
V_{in}	Input voltage ⁽³⁾	$V_{DD}-0.2$ to $V_{CC}+0.2$	V
T_{stg}	Storage temperature	-65 to +150	°C
R_{thja}	Thermal resistance junction to ambient ^{(4) (5)}		°C/W
	SOT23-5	250	
	SO-8	125	
	MiniSO-8	190	
	SO-14	103	
	TSSOP14	100	
R_{thjc}	Thermal resistance junction to case		°C/W
	SOT23-5	81	
	SO-8	40	
	MiniSO8	39	
	SO14	31	
	TSSOP14	32	
T_j	Maximum junction temperature	150	°C
ESD	HBM: human body model ⁽⁶⁾	5	kV
	MM: machine model ⁽⁷⁾	400	V
	CDM: charged device model ⁽⁸⁾		
	SOT23-5, SO-8, MSO8, SO14 TSSOP14	1500 750	V
	Latch-up immunity	200	mA

1. Value with respect to V_{DD} pin.
2. Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
3. $V_{CC}-V_{in}$ must not exceed 6V.
4. Short-circuits can cause excessive heating and destructive dissipation.
5. R_{th} are typical values.
6. Human body model: 100pF discharged through a 1.5kΩ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
7. Machine model: 200pF is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor $< 5\Omega$), done for all couples of pin combinations with other pins floating.
8. Charged device model: all pins plus package are charged together to the specified voltage and then discharged directly to the ground.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	2.5 to 5.5	V
V_{icm}	Common mode input voltage range	$V_{DD} -0.1$ to $V_{CC} +0.1$	V
T_{oper}	Operating free air temperature range	-40 to +125	°C

2 Electrical characteristics

Table 3. Electrical characteristics at $V_{CC} = +2.5V$, $V_{DD} = 0V$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25^{\circ}C$, R_L connected to $V_{CC}/2$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
DC performance							
V_{io}	Offset voltage TSV99x		-	0.1	4.5	mV	
		$T_{min} < T_{op} < T_{max}$	-	-	7.5		
	TSV99xA		-	-	1.5		
		$T_{min} < T_{op} < T_{max}$	-	-	3		
DV_{io}	Input offset voltage drift		-	2	-	$\mu V/{}^{\circ}C$	
I_{io}	Input offset current ⁽¹⁾ ($V_{out} = V_{CC}/2$)		-	1	10	pA	
I_{ib}	Input bias current ⁽¹⁾ ($V_{out} = V_{CC}/2$)		-	1	10	pA	
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	0V to 2.5V, $V_{out} = 1.25V$	58	75	-	dB	
A_{vd}	Large signal voltage gain	$R_L = 10k\Omega$ $V_{out} = 0.5V$ to 2V	80	89	-	dB	
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV	
V_{OL}	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV	
I_{out}	I_{sink}	$V_o = 2.5V$	18	32	-	mA	
		$T_{min} < T_{amb} < T_{max}$	16	-	-		
	I_{source}	$V_o = 0V$	18	35	-		
		$T_{min} < T_{amb} < T_{max}$	16	-	-		
I_{CC}	Supply current (per operator)		No load, $V_{out}=V_{CC}/2$	-	0.78	1.1	mA
			$T_{min} < T_{op} < T_{max}$	-	-	1.1	
AC performance							
GBP	Gain bandwidth product	$R_L = 2k\Omega$, $C_L = 100pF$, $f = 100kHz$	-	20	-	MHz	
ϕm	Phase margin	$R_L = 2k\Omega$, $C_L = 100pF$, $G=5$, $f=100kHz$	-	60	-	Degrees	
G_m	Gain margin	$R_L = 2k\Omega$, $C_L = 100pF$, $\phi m=40^{\circ}$	-	2.5	-	dB	
SR	Slew rate	$R_L = 2k\Omega$, $C_L = 100pF$	-	10	-	V/ μ s	
e_n	Equivalent input noise voltage	$f=10kHz$	-	21	-	$\frac{nV}{\sqrt{Hz}}$	
THD+ e_n	Total harmonic distortion	$G=1$, $f=1kHz$, $R_L=2k\Omega$, $BW=22kHz$, $V_{icm}=(V_{cc}+1)/2$, $V_{out}=1.1V_{pp}$	-	0.0017	-	%	

1. Guaranteed by design.

Table 4. Electrical characteristics at $V_{CC} = +3.3V$, $V_{DD} = 0V$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25^\circ C$, R_L connected to $V_{CC}/2$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
DC performance							
V_{io}	Offset voltage TSV99x		-	0.1	4.5	mV	
		$T_{min} < T_{op} < T_{max}$	-	-	7.5		
	TSV99xA		-	-	1.5		
		$T_{min} < T_{op} < T_{max}$	-	-	3		
DV_{io}	Input offset voltage drift		-	2	-	$\mu V/^\circ C$	
I_{io}	Input offset current ⁽¹⁾		-	1	10	pA	
I_{ib}	Input bias current ⁽¹⁾		-	1	10	pA	
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	0V to 3.3V, $V_{out} = 1.65V$	60	78	-	dB	
A_{vd}	Large signal voltage gain	$R_L=10k\Omega$ $V_{out}=0.5V$ to $2.8V$	80	90	-	dB	
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV	
V_{OL}	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV	
I_{out}	I_{sink}	$V_o = 3.3V$	18	32	-	mA	
		$T_{min} < T_{amb} < T_{max}$	16	-	-		
	I_{source}	$V_o = 0V$	18	35	-		
		$T_{min} < T_{amb} < T_{max}$	16	-	-		
I_{CC}	Supply current (per operator)		No load, $V_{out}=V_{CC}/2$	-	0.8	1.1	mA
			$T_{min} < T_{op} < T_{max}$	-	-	1.1	
AC performance							
GBP	Gain bandwidth product	$R_L = 2k\Omega$ $C_L = 100pF$, $f = 100kHz$	-	20	-	MHz	
ϕ_m	Phase margin	$R_L = 2k\Omega$ $C_L = 100pF$, $G=5$	-	60	-	Degrees	
G_m	Gain margin	$R_L = 2k\Omega$ $C_L = 100pF$, $f = 100kHz$, $\phi_m=40^\circ$	-	2.5	-	dB	
SR	Slew rate	$R_L = 2k\Omega$ $C_L = 100pF$, $f = 100kHz$	-	10	-	$V/\mu s$	
e_n	Equivalent input noise voltage	$f=10kHz$	-	21	-	nV/\sqrt{Hz}	
THD+ e_n	Total harmonic distortion	$G=1$, $f=1kHz$, $R_L=2k\Omega$, $BW=22kHz$, $V_{icm}=(V_{cc}+1)/2$, $V_{out}=1.9V_{pp}$	-	0.001	-	%	

1. Guaranteed by design.

Table 5. Electrical characteristics at $V_{CC} = +5V$, $V_{DD} = 0V$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25^{\circ}C$, R_L connected to $V_{CC}/2$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
DC performance						
V_{io}	Offset voltage TSV99x		-	0.1	4.5	mV
		$T_{min} < T_{op} < T_{max}$	-	-	7.5	
	TSV99xA		-	-	1.5	
		$T_{min} < T_{op} < T_{max}$	-	-	3	
DV_{io}	Input offset voltage drift		-	2	-	$\mu V/{\circ}C$
I_{io}	Input offset current ⁽¹⁾		-	1	10	pA
I_{ib}	Input bias current ⁽¹⁾		-	1	10	pA
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	$0V$ to $5V$, $V_{out} = 2.5V$	62	82	-	dB
SVR	Supply voltage rejection ratio $20 \log (\Delta V_{cc}/\Delta V_{io})$	$V_{CC} = 2.5$ to $5V$	70	86	-	dB
A_{vd}	Large signal voltage gain	$R_L=10k\Omega$ $V_{out}=0.5V$ to $4.5V$	80	91	-	dB
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV
V_{OL}	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV
I_{out}	I_{sink}	$V_o = 5V$	18	32	-	mA
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
	I_{source}	$V_o = 0V$	18	35	-	
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
I_{CC}	Supply current (per operator)	No load, $V_{out}=2.5V$	-	0.82	1.1	mA
		$T_{min} < T_{op} < T_{max}$	-	-	1.1	
AC performance						
GBP	Gain bandwidth product	$R_L = 2k\Omega$ $C_L = 100pF$, $f = 100kHz$	-	20	-	MHz
ϕ_m	Phase margin	$R_L = 2k\Omega$ $C_L = 100pF$, $G=5$	-	60	-	Degrees
G_m	Gain margin	$R_L = 2k\Omega$ $C_L=100pF$, $\phi_m=40^{\circ}$	-	2.5	-	dB
SR	Slew rate	$R_L = 2k\Omega$ $C_L = 100pF$	-	10	-	V/ μ s
e_n	Equivalent input noise voltage	$f=10kHz$	-	21	-	nV/\sqrt{Hz}
THD+ e_n	Total harmonic distortion	$G=1$, $f=1kHz$, $R_L=2k\Omega$, $BW=22kHz$, $Vicm=(V_{cc}+1)/2$, $V_{out}=3.6V_{pp}$	-	0.0007	-	%

1. Guaranteed by design.

Figure 1. Input offset voltage distribution at T=25°C

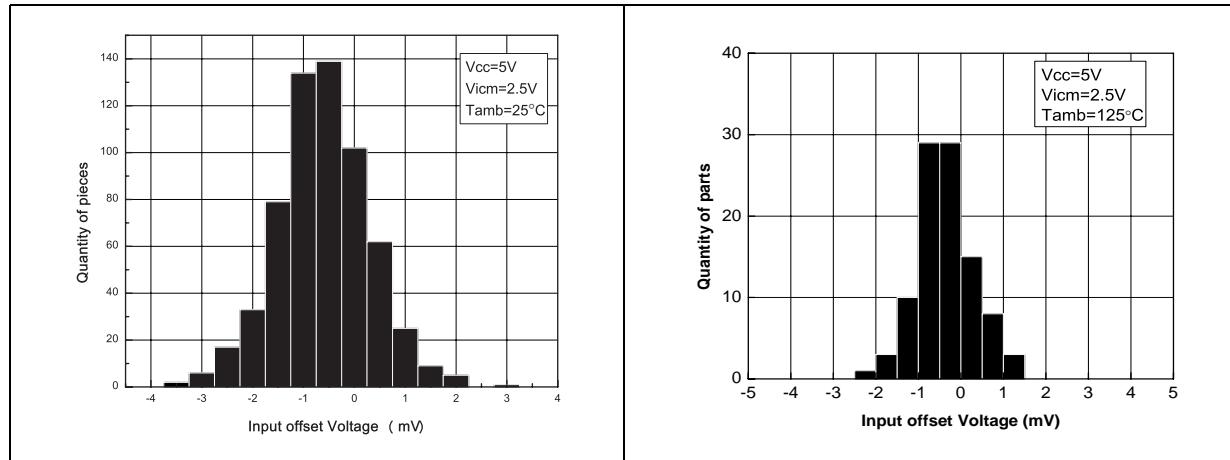


Figure 2. Input offset voltage distribution at T=125°C

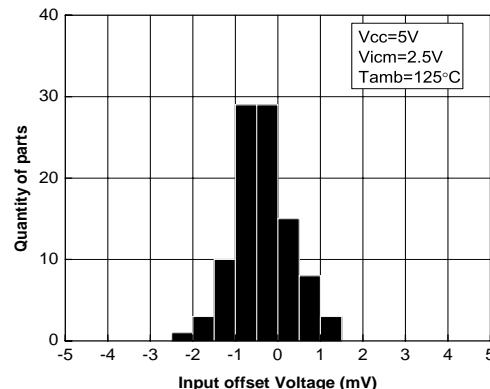


Figure 3. Supply current vs. input common mode voltage at V_{CC}=2.5V

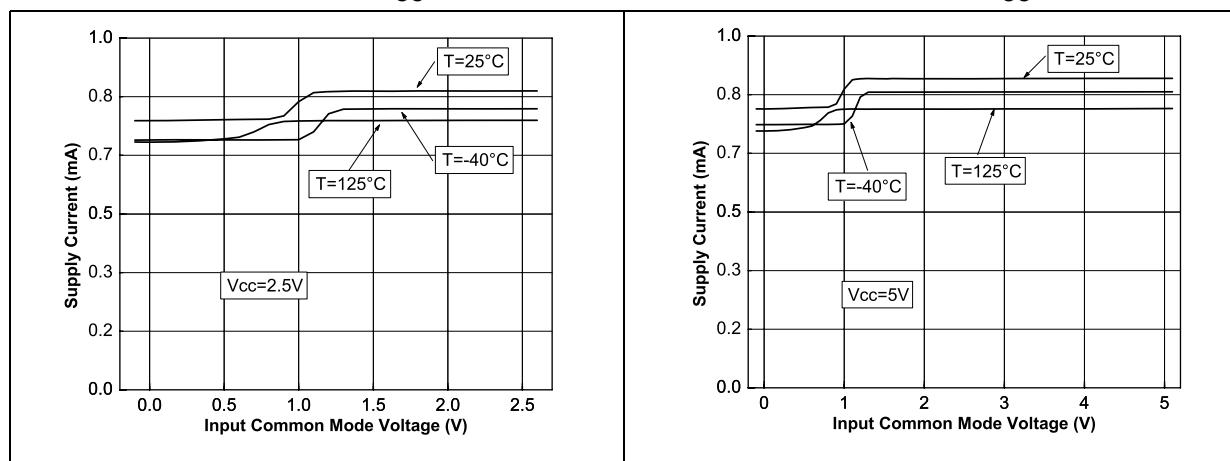


Figure 4. Supply current vs. input common mode voltage at V_{CC}=5V

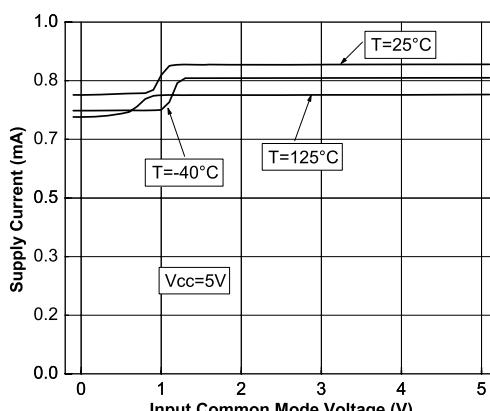


Figure 5. Output current vs. output voltage at V_{CC}=2.5V

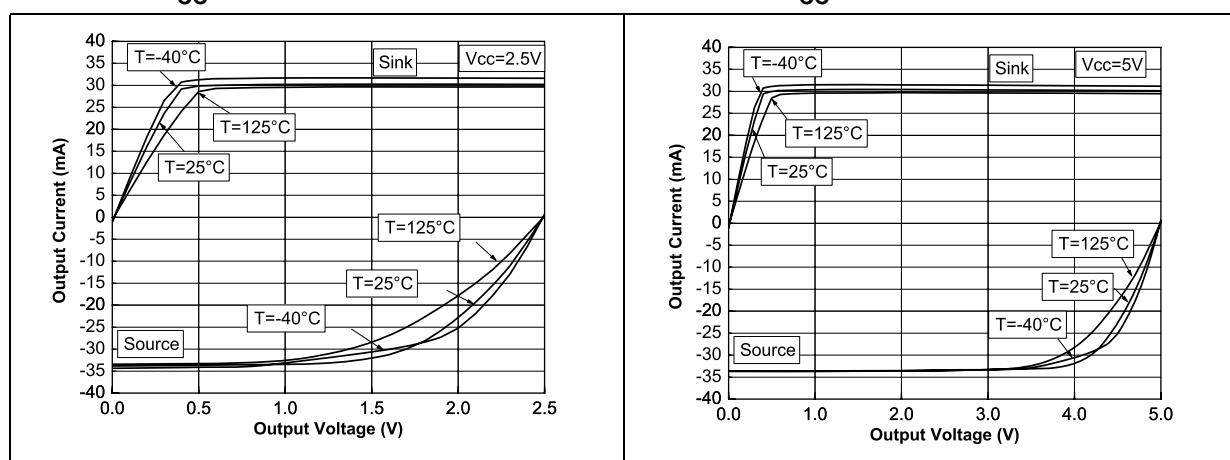


Figure 6. Output current vs. output voltage at V_{CC}=5V

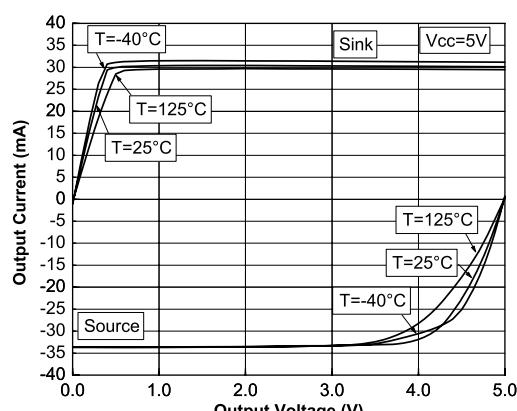


Figure 7. Voltage gain and phase vs frequency at $V_{CC}=5V$ and $V_{icm}=0.5V$

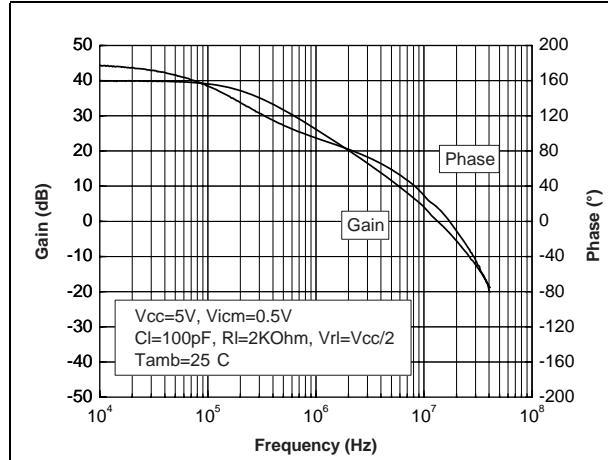


Figure 8. Voltage gain and phase vs frequency at $V_{CC}=5V$ and $V_{icm}=2.5V$

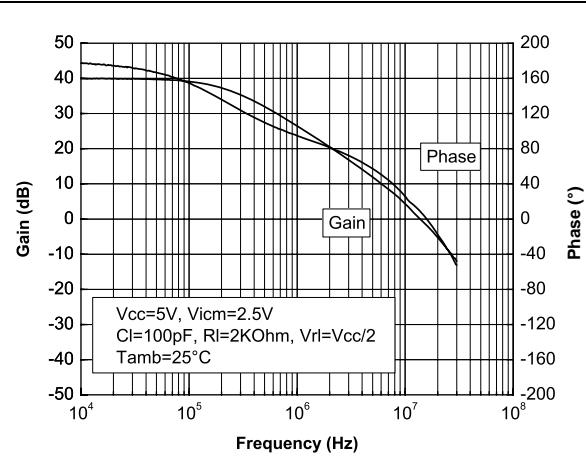


Figure 9. Positive slew rate

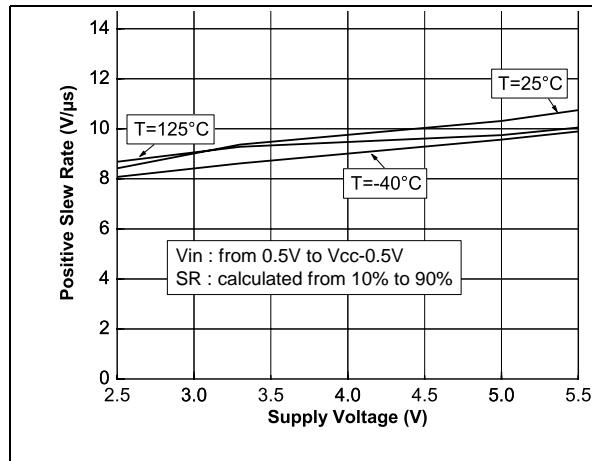


Figure 10. Negative slew rate

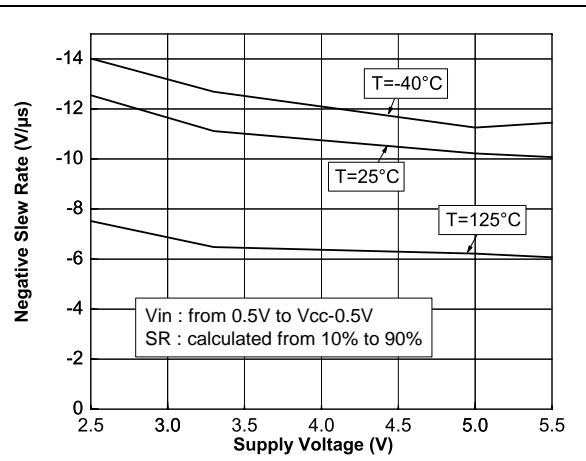


Figure 11. Distortion + noise vs. frequency

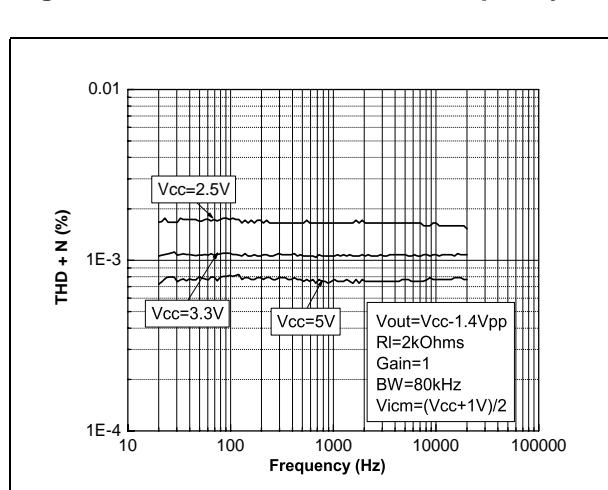


Figure 12. Distortion + noise vs. output voltage

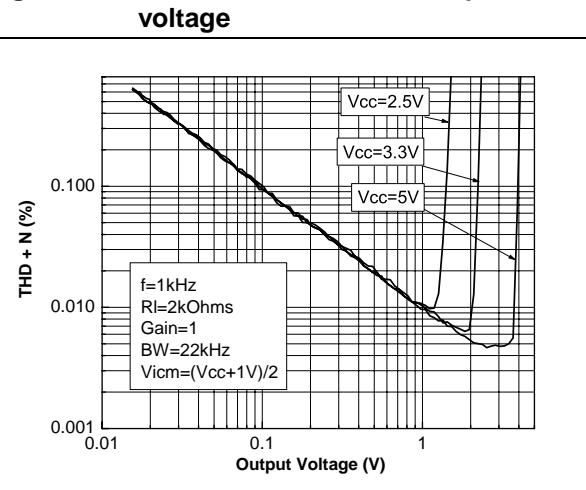
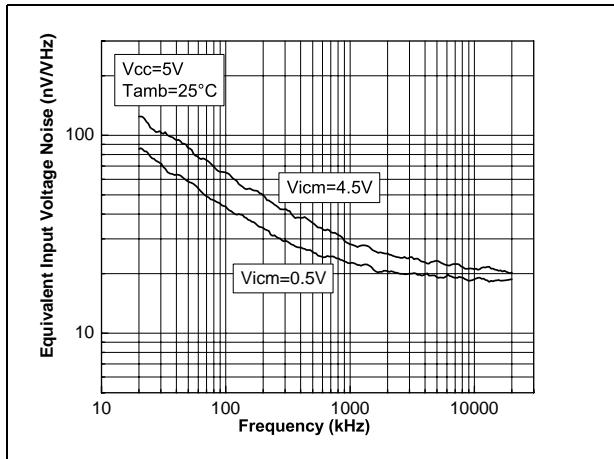


Figure 13. Noise vs. frequency

3 Package information

In order to meet environmental requirements, STMicroelectronics offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an STMicroelectronics trademark. ECOPACK specifications are available at: www.st.com.

Figure 14. SOT23-5 package

Ref.	Dimensions					
	Millimeters			Mils		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.45	35.4		57.1
A1	0.00		0.15	0.00		5.9
A2	0.90		1.30	35.4		51.2
b	0.35		0.50	13.7		19.7
C	0.09		0.20	3.5		7.8
D	2.80		3.00	110.2		118.1
E	2.60		3.00	102.3		118.1
E1	1.50		1.75	59.0		68.8
e		0.95			37.4	
e1		1.9			74.8	
L	0.35		0.55	13.7		21.6

The diagram illustrates the physical dimensions of the SOT23-5 package. The left side shows a front view with dimensions A (width), A1 (lead thickness), A2 (lead spread), C (lead pitch), and L (lead height). The right side shows a top-down view with dimensions D (body width), E (body height), E1 (body thickness), b (body thickness), and e (body thickness). The package is shown in a lead-free ECOPACK version.

Figure 15. MiniSO-8 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.1			0.043
A1	0.05	0.10	0.15	0.002	0.004	0.006
A2	0.78	0.86	0.94	0.031	0.034	0.037
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	4.75	4.90	5.05	0.187	0.193	0.199
E1	2.90	3.00	3.10	0.114	0.118	0.122
e		0.65			0.026	
K	0°		6°	0°		6°
L	0.40	0.55	0.70	0.016	0.022	0.028
L1			0.10			0.04

The figure contains three technical drawings of the MiniSO-8 package. The top drawing shows a side cross-sectional view with dimensions: A (height) = 1.1 mm, A1 (lead thickness) = 0.10 mm, A2 (lead width) = 0.78 mm, b (lead pitch) = 0.25 mm, c (lead height) = 0.13 mm, D (width) = 2.90 mm, E (length) = 4.75 mm, L (lead thickness) = 0.40 mm, L1 (lead height) = 0.10 mm, and k (lead lead-in angle) = 6°. It also indicates the GAGE PLANE and SEATING PLANE. The bottom-left drawing shows a top-down view with dimensions A, A1, A2, b, c, D, E, and L. The bottom-right drawing shows the chip layout with pins numbered 1 through 8, and a dot indicating PIN 1 IDENTIFICATION.

Figure 16. SO-8 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.04		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.150		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.1			0.04

The figure contains three technical drawings of an SO-8 package. The top drawing shows a side cross-section with dimensions D, A, A1, A2, B, and e. The bottom-left drawing shows a top-down view with pins numbered 1 through 8 and dimensions E and H. The bottom-right drawing shows a bottom cross-section with a seating plane at height C, a gage plane at 0.25 mm, and a lead angle of h x 45°. Dimensions L and k are also indicated.

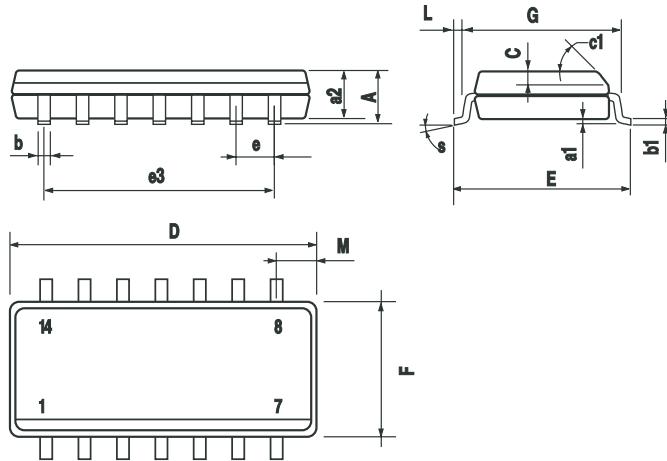
Figure 17. TSSOP14 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L1	0.45	0.60	0.75	0.018	0.024	0.030

The technical drawing illustrates the physical dimensions of the TSSOP14 package. It shows a top-down view of the package with various dimensions labeled: A (total height), A1 (lead thickness), A2 (lead spacing), b (lead width), c (lead pitch), D (total width), E (total length), E1 (body length), and K (lead angle). A callout provides a detailed view of the lead profile with dimensions L and E. A circular feature on the package body is labeled 'PIN 1 IDENTIFICATION' with a number '1' below it.

Figure 18. SO-14 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					



The technical drawing illustrates the physical dimensions of the SO-14 package. It includes three views: a top view showing the 14 pins and their positions (1, 7, 8, 14), a side cross-sectional view showing height dimensions like A, a1, a2, and C, and a bottom view showing the lead profile with dimensions D, E, F, G, L, M, and S. The drawing also indicates the lead angle (c1) and the lead pitch (e3).

4 Ordering information

Part number	Temperature range	Package	Packing	Marking	
TSV991ILT	-40°C to +125°C	SOT23-5	Tape & reel	K130	
TSV991AILT				K129	
TSV992IST		MiniSO-8		K132	
TSV992AIST				K135	
TSV992ID		SO-8	Tube or tape & reel	V992I	
TSV992IDT				V992AI	
TSV992AID		TSSOP14	Tape & reel	V994I	
TSV992AIDT				V994AI	
TSV994IPT		SO-14	Tube or tape & reel	V994I	
TSV994AIPT				V994AI	
TSV994ID					
TSV994IDT					
TSV994AID					
TSV994AIDT					

5 Revision history

Date	Revision	Changes
31-Jul-2006	1	Preliminary data release for product under development.
7-Nov-2006	2	Final version of datasheet.
12-Dec-2006	3	Noise and distortion figures added.

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